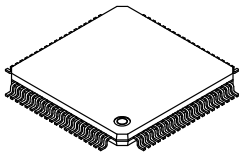
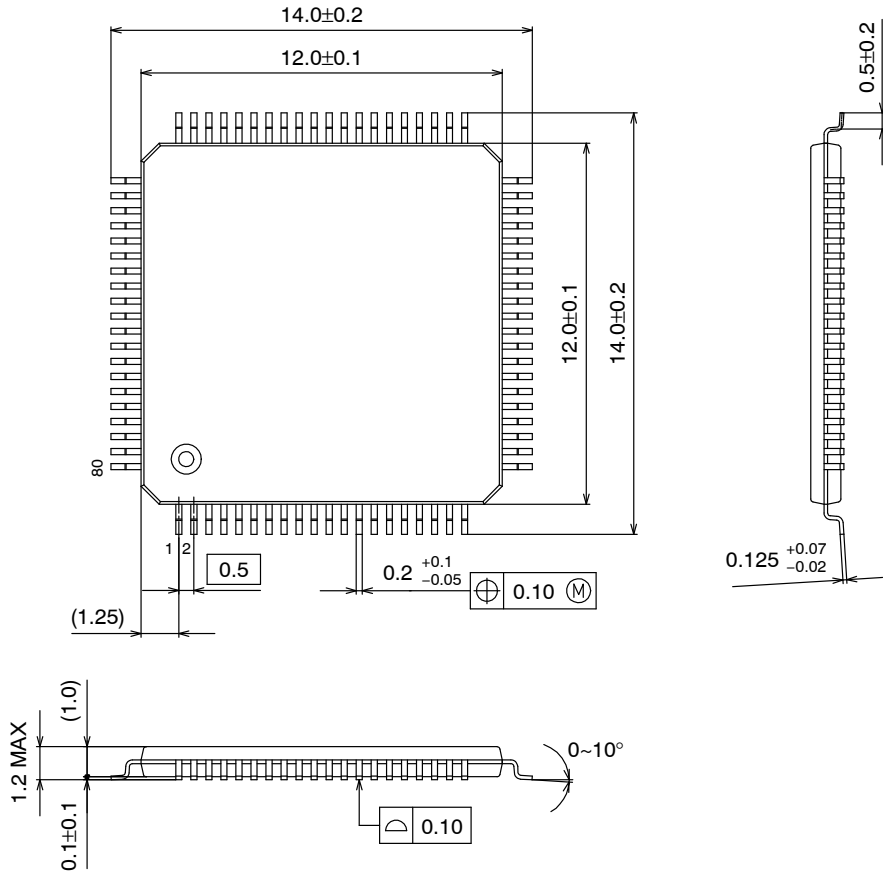


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

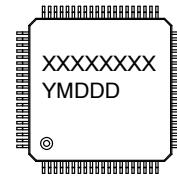


**TQFP80 12x12 / TQFP80J**  
**CASE 932AX**  
**ISSUE A**

DATE 07 NOV 2013



**GENERIC MARKING DIAGRAM\***

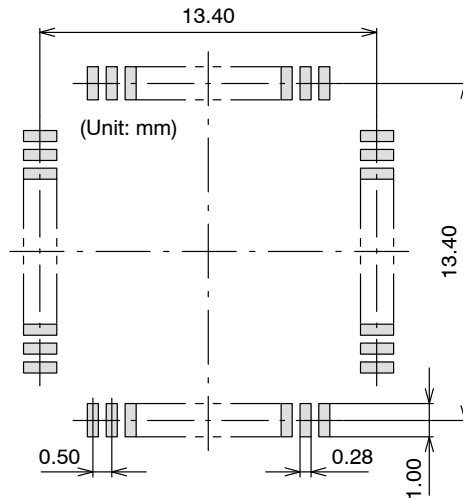


XXXXX = Specific Device Code  
 Y = Year  
 M = Month  
 DDD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

<b>DOCUMENT NUMBER:</b>	<b>98AON67109E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>TQFP80 12X12 / TQFP80J</b>	<b>PAGE 1 OF 3</b>

**SOLDERING FOOTPRINT\***



NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

<b>DOCUMENT NUMBER:</b>	<b>98AON67109E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>TQFP80 12X12 / TQFP80J</b>	<b>PAGE 2 OF 3</b>

